

**Assembly Transfer of Large Body Punched LFCSP Products to Amkor Philippines
AP1**

**Qualification Results Summary of Punched, Top Exposed
Pad LFCSP at Amkor Philippines**

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	Pass
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 32	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Pass
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 32	Pass
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass ±1250V

*Preconditioned per JEDEC/IPC J-STD-020